



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
 United States Patent and Trademark Office
 Address: COMMISSIONER FOR PATENTS
 P.O. Box 1450
 Alexandria, Virginia 22313-1450
 www.uspto.gov



Bib Data Sheet

CONFIRMATION NO. 7910

SERIAL NUMBER 10/500,119	FILING OR 371(c) DATE 06/17/2005 RULE	CLASS 174	GROUP ART UNIT 2841	ATTORNEY DOCKET NO. 1204.43988X00
APPLICANTS Hidehiro Nakamura, Tsukuba-shi, JAPAN; Akishi Nakaso, Oyama-shi, JAPAN; Shigeharu Arike, Shimodate-shi, JAPAN; Fumio Inoue, Tsukuba-shi, JAPAN; Tetsuya Enomoto, Tsukuba-shi, JAPAN; Norio Moriike, Shimodate-shi, JAPAN; Kousuke Hiroki, Tsukuba-shi, JAPAN;				
** CONTINUING DATA ***** This application is a 371 of PCT/JP02/13434 12/24/2002 <i>YES</i> <i>IBP</i>				
** FOREIGN APPLICATIONS ***** <input checked="" type="checkbox"/> JAPAN 2001-391799 12/25/2001 <i>YES</i> <input checked="" type="checkbox"/> JAPAN 2002-126594 04/26/2002 <i>IBP</i> <input checked="" type="checkbox"/> JAPAN 2002-230095 08/07/2002				
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance Verified and Acknowledged <i>IBP</i> Examiner's Signature _____ Initials _____		STATE OR COUNTRY JAPAN	SHEETS DRAWING 8	TOTAL CLAIMS 39
INDEPENDENT CLAIMS 2				
ADDRESS 20457				
TITLE Connection substrate, multi-layer wiring board using the connection substrate, substrate for semiconductor package, and methods for manufacturing them				
FILING FEE RECEIVED 2492	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	